RoHS

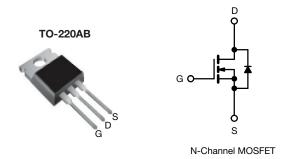
COMPLIANT HALOGEN

**FREE** 



# **E Series Power MOSFET with Fast Body Diode**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V	0.102		
Q <sub>g</sub> max. (nC)	146			
Q <sub>gs</sub> (nC)	21			
Q <sub>gd</sub> (nC)	43			
Configuration	Single			



## **FEATURES**

- Fast body diode MOSFET using E series technology
- Reduced t<sub>rr</sub>, Q<sub>rr</sub>, and I<sub>RRM</sub>
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Low switching losses due to reduced Q<sub>rr</sub>
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- Telecommunications
  - Server and telecom power supplies
- Lighting
  - High intensity discharge (HID)
  - Light emitting diodes (LEDs)
- Consumer and computing
  - ATX power supplies
- Industrial
  - Welding
  - Battery chargers
- Renewable energy
  - Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- Applications using the following topologies
  - LLC
  - Phase shifted bridge (ZVS)
  - 3-level inverter
  - AC/DC bridge

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free and halogen-free	SiHP28N65EF-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	650	.,	
Gate-source voltage			$V_{GS}$	± 30	V	
Continuous drain current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 100 °C		28		
		T <sub>C</sub> = 100 °C	I <sub>D</sub>	18	A	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	87		
Linear derating factor				2	W/°C	
Single pulse avalanche energy b			E <sub>AS</sub>	427	mJ	
Maximum power dissipation			$P_{D}$	250	W	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-source voltage slope	T <sub>J</sub> = 125 °C		dV/dt 70 11	1//		
Reverse diode dV/dt <sup>d</sup>	erse diode dV/dt <sup>d</sup>			11	- V/ns	
Soldering recommendations (peak temperature) c	for 10 s			300	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b.  $V_{DD}$  = 140 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 5.5 A
- c. 1.6 mm from case
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$



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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	°C/W		
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.5	C/ VV		

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		•			I.	·	
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	650	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 10 mA	-	0.74	-	V/°C
Gate-source threshold voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	4.0	V
		V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	V <sub>GS</sub> = ± 30 V		-	± 1	μΑ
		V <sub>DS</sub> =	: 520 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 520 V	', V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	500	
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 14 A	-	0.102	0.117	Ω
Forward transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 30 V, I <sub>D</sub> = 14 A		-	11	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1  MHz		-	3249	-	pF
Output capacitance	C <sub>oss</sub>			-	145	-	
Reverse transfer capacitance	C <sub>rss</sub>			-	5	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 0 V to 520 V		-	105	-	
Effective output capacitance, time related b	C <sub>o(tr)</sub>			-	441	-	
Total gate charge	Qg		V <sub>GS</sub> = 10 V	-	97	146	nC
Gate-source charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$		-	21	-	
Gate-drain charge	Q <sub>gd</sub>	]		-	43	-	
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD} = 520 \text{ V}, I_{D} = 14 \text{ A}$ $R_{g} = 9.1 \Omega, V_{GS} = 10 \text{ V}$		-	29	58	- ns
Rise time	t <sub>r</sub>			-	44	88	
Turn-off delay time	t <sub>d(off)</sub>			-	93	140	
Fall time	t <sub>f</sub>			-	51	102	
Gate input resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.25	0.5	1.0	Ω
<b>Drain-Source Body Diode Characteristics</b>							
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	28	
Pulsed diode forward current	I <sub>SM</sub>			-	-	87	- A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 11 A, V <sub>GS</sub> = 0 V		-	0.9	1.2	V
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S = 14 A</sub> , dI/dt = 100 A/μs, V <sub>R</sub> = 400 V		-	174	308	ns
Reverse recovery charge	Q <sub>rr</sub>			-	1.1	2.4	μC
Reverse recovery current	I <sub>RRM</sub>			-	15	-	Α

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

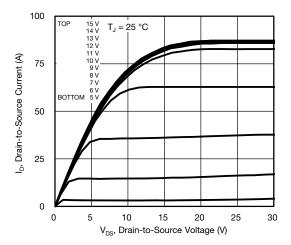


Fig. 1 - Typical Output Characteristics

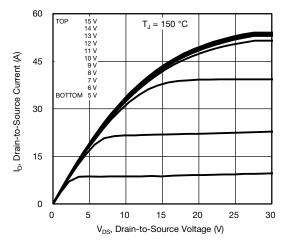


Fig. 2 - Typical Output Characteristics

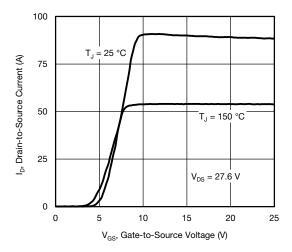


Fig. 3 - Typical Transfer Characteristics

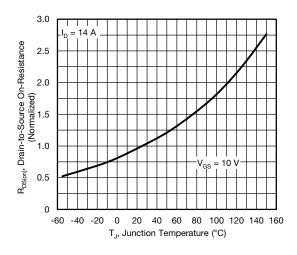


Fig. 4 - Normalized On-Resistance vs. Temperature

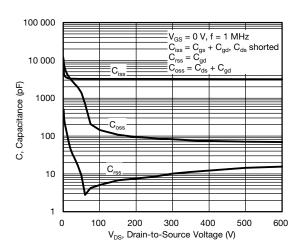


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

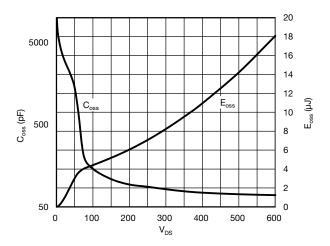


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



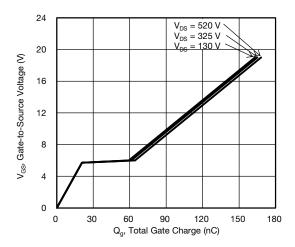


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

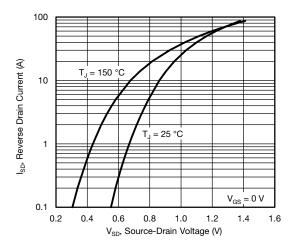


Fig. 8 - Typical Source-Drain Diode Forward Voltage

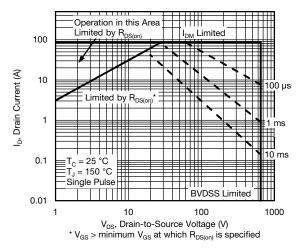


Fig. 9 - Maximum Safe Operating Area

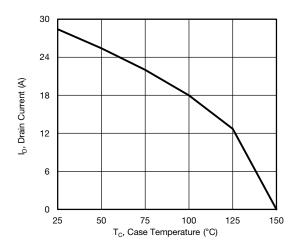


Fig. 10 - Maximum Drain Current vs. Case Temperature

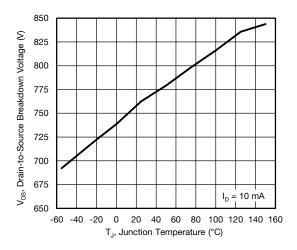


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature



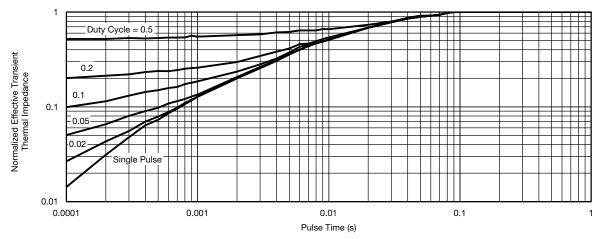


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

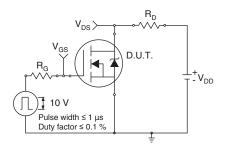


Fig. 13 - Switching Time Test Circuit

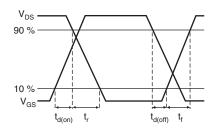


Fig. 14 - Switching Time Waveforms

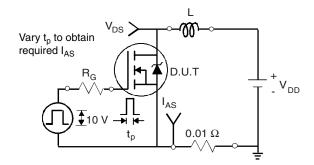


Fig. 15 - Unclamped Inductive Test Circuit

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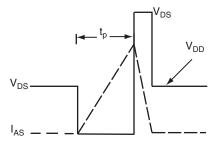


Fig. 16 - Unclamped Inductive Waveforms

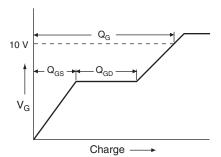


Fig. 17 - Basic Gate Charge Waveform

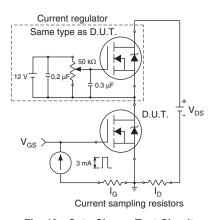
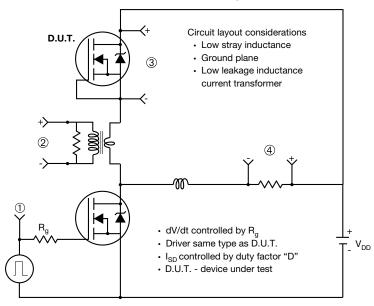


Fig. 18 - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



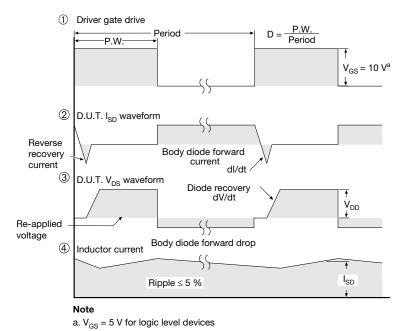


Fig. 19 - For N-Channel

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